RELIABILITY REPORT

FOR

MAX6709xUB

PLASTIC ENCAPSULATED DEVICES

September 30, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Conclusion

The MAX6709 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

The MAX6709 quad voltage monitor provides accurate monitoring of up to four supplies without any external components. A variety of factory-trimmed threshold voltages and supply tolerances are available to optimize the MAX6709/ for specific applications. The selection includes input options for monitoring 5.0V, 3.3V, 3.0V, 2.5V, and 1.8V voltages. Additional high-input-impedance comparator options can be used as adjustable voltage monitors, general-purpose comparators, or digital-level translators.

The MAX6709 provides four independent open-drain outputs with 10µA internal pullup to V_{CC}

Each of the monitored voltages is available with trip thresholds to support power-supply tolerances of either 5% or 10% below the nominal voltage. An internal bandgap reference ensures accurate trip thresholds across the operating temperature range.

The MAX6709 consumes only 35µA (typ) of supply current. The MAX6709 operates with supply voltages of 2.0V to 5.5V. An internal undervoltage lockout circuit forces all four digital outputs low when V_{CC} drops below the minimum operating voltage. The four digital outputs have weak internal pullups to V_{CC}, accommodating wire-ORed connections. Each input threshold voltage has an independent output. The MAX6709 is available in a 10-pin µMAX package and operates over the extended (-40°C to +85°C) temperature range.

B. Absolute Maximum Ratings

Item	Rating
All Pins to GND	-0.3V to +6V
Input/Output Current (all pins)	20mA
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Power Dissipation	
10-Pin µMAX	444mW
Derates above +70°C	
10-Pin µMAX	5.6mW/°C

II. Manufacturing Information

A. Description/Function:	Low-Voltage, High-Accuracy, Quad Voltage Monitor in µMAX Package
B. Process:	S8 (Standard .8 micron silicon gate CMOS)
C. Number of Device Transistors:	1029
D. Fabrication Location:	California, USA
E. Assembly Location:	Malaysia, Thailand or Philippines
F. Date of Initial Production:	July, 2002

III. Packaging Information

A. Package Type:	**10-Pin µMAX**
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-Filled Epoxy
E. Bondwire:	Gold (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-1601-0174
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	56 x 34 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Copper/Silicon
D. Backside Metallization:	None
E. Minimum Metal Width:	.8 microns (as drawn)
F. Minimum Metal Spacing:	.8 microns (as drawn)
G. Bondpad Dimensions:	2.7 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:

Jim Pedicord	(Manager, Reliability Operations)
Bryan Preeshl	(Executive Director of QA)
Kenneth Huening	(Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(4389: Thermal acceleration factor assuming a 0.8eV activation energy)

$\lambda = 13.57 \times 10^{-9}$ λ= 13.57 F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure the reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on lots exceeding this level. The following Burn-In Schematic (Spec. #06-5556) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The MS71 die type has been found to have all pins able to withstand a transient pulse of 2500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX6709xUB

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0
Moisture Testing (Note 2)				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots.
Note 2: Generic package/process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

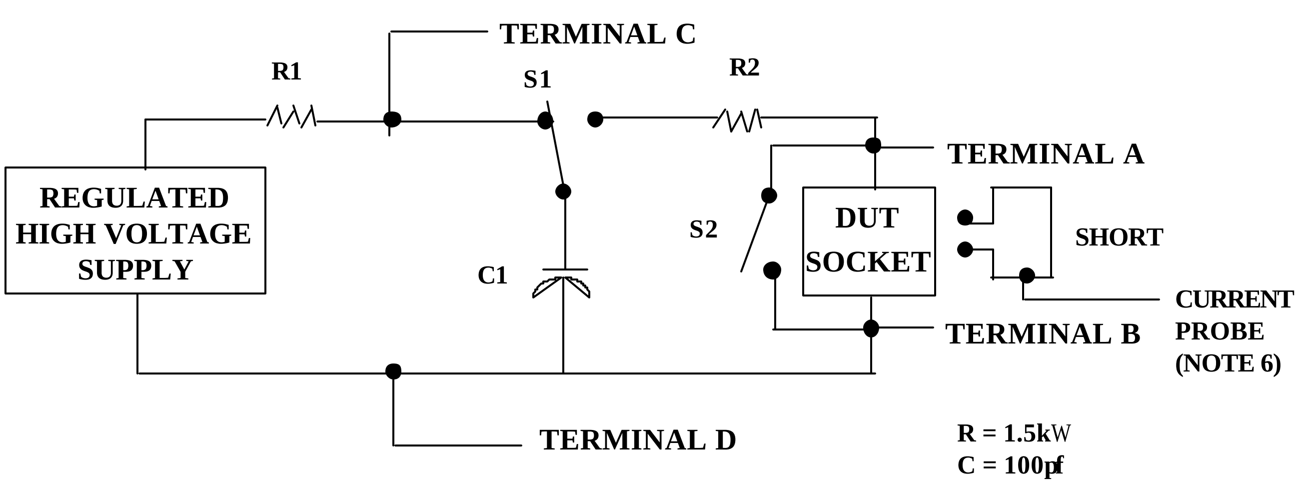
1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground (e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

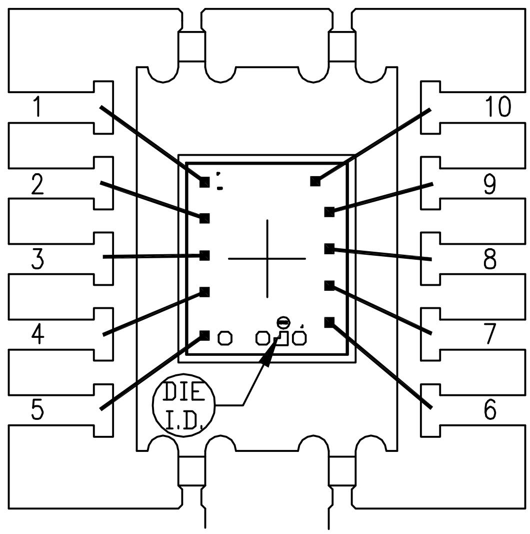
3.4 Pin combinations to be tested.

a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

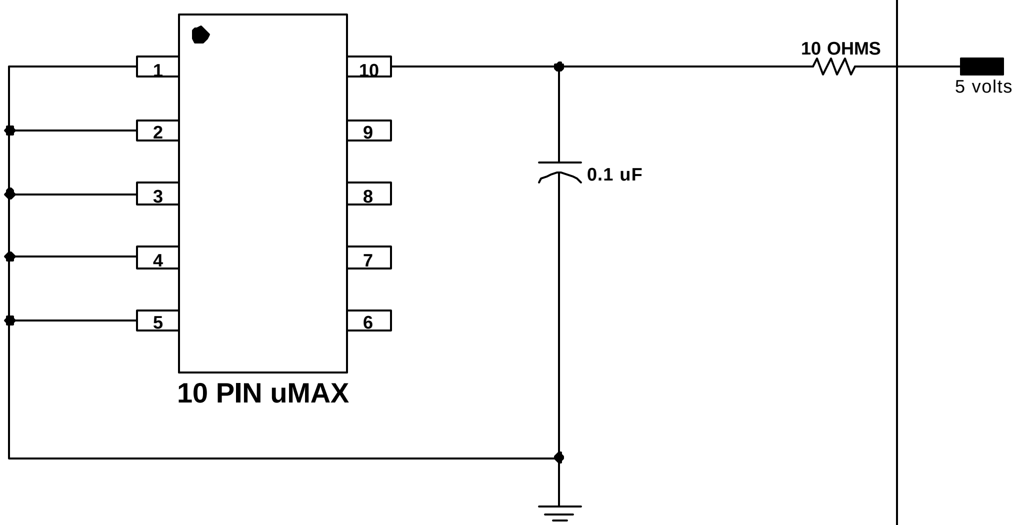
c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG. CODE: U10-2		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY
CAV./PAD SIZE: 68x94	PKG.			BOND DIAGRAM #: 05-1601-0174 / REV: A
	DESIGN			

ONCE PER SOCKET	ONCE PER BOARD



DEVICES: MAX6338/6709/6714

MAX. EXPECTED CURRENT = 60uA

DRAWN BY: TEK TAN
NOTES: